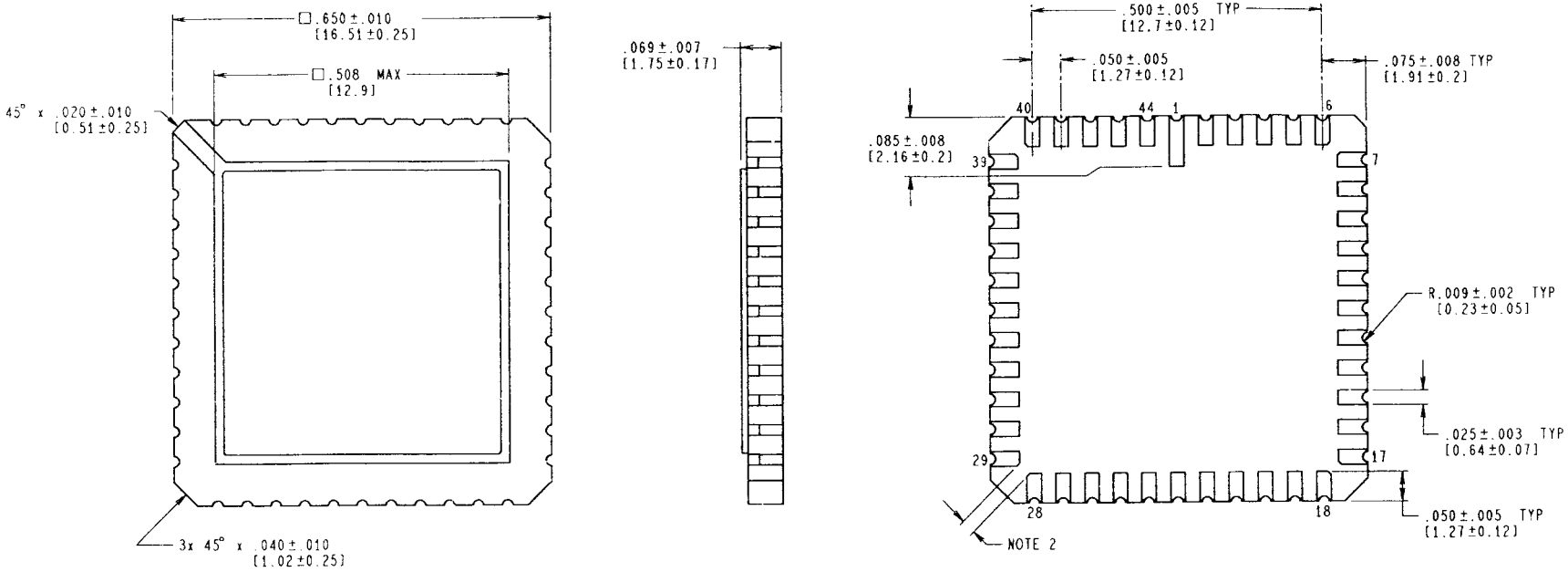
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE AND REDRAW PER NEW STANDARD.	10006	02/17/94	DEG/



CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:

   a. 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICROINCHES/1.27-8.89 MICROMETERS NICKEL.

   b. SOLDER DIP.
   SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.

2. CORNER PADS MAY HAVE A 45°X.020IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE .015IN/0.38mm DIMENSION.

4. REFERENCE JEDEC REGISTRATION MS-004, VARIATION CD, DATED 7/90.

MIL/AERO CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN Dwayne Grady	02/17/94
DES. CHK.	3/03/94
ENGR. CHK.	3-4-94
APPROVAL	

NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

LEADLESS CHIP CARRIER, TYPE C, 44 TERMINAL

PROJECTION INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-E44A	F

DO NOT SCALE DRAWING — SHEET 1 of 1